

## N-Channel Enhancement Mode Power MOSFET

<p><b>Description</b></p> <p>The GT025N06AD5 uses advanced trench technology to provide excellent <math>R_{DS(ON)}</math>, low gate charge. It can be used in a wide variety of applications.</p> <p><b>General Features</b></p> <ul style="list-style-type: none"> <li>● <math>V_{DS}</math> 60V</li> <li>● <math>I_D</math> (at <math>V_{GS} = 10V</math>) 170A</li> <li>● <math>R_{DS(ON)}</math> (at <math>V_{GS} = 10V</math>) &lt; 2.2mΩ</li> <li>● <math>R_{DS(ON)}</math> (at <math>V_{GS} = 4.5V</math>) &lt; 2.8mΩ</li> <li>● 100% Avalanche Tested</li> <li>● RoHS Compliant</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>● Power switch</li> <li>● DC/DC converters</li> </ul>	<p>Schematic diagram</p> <p>pin assignment</p> <p>DFN5*6-8L</p>		
<b>Ordering Information</b>			
<b>Device</b>	<b>Package</b>	<b>Marking</b>	<b>Packaging</b>
GT025N06AD5	DFN5*6-8L	GT025N06	5000pcs/Reel

<b>Absolute Maximum Ratings</b> $T_C = 25^\circ\text{C}$ , unless otherwise noted				
Parameter	Symbol	Value	Unit	
Drain-Source Voltage	$V_{DS}$	60	V	
Continuous Drain Current	$I_D$	170	A	
$T_C = 100^\circ\text{C}$		107		
Pulsed Drain Current (note1)	$I_{DM}$	680	A	
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V	
Power Dissipation	$P_D$	215	W	
Single pulse avalanche energy (note2)	$E_{AS}$	324	mJ	
Operating Junction and Storage Temperature Range	$T_J$ , $T_{stg}$	-55 To 150	°C	

<b>Thermal Resistance</b>				
Parameter	Symbol	Value	Unit	
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	50	°C/W	
Thermal Resistance, Junction-to-Case	$R_{thJC}$	0.58	°C/W	

**Specifications**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	60	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 60\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	1	$\mu\text{A}$
Gate-Source Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 20\text{V}$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.2	1.7	2.5	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$	--	1.8	2.2	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 12\text{A}$	--	2.3	2.8	
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{GS}} = 5\text{V}, I_D = 20\text{A}$	--	62	--	S
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 30\text{V}, f = 1.0\text{MHz}$	--	5100	--	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		--	1350	--	
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	70	--	
Total Gate Charge	$Q_g$	$V_{\text{DD}} = 30\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$	--	102	--	$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$		--	14	--	
Gate-Drain Charge	$Q_{\text{gd}}$		--	23	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 30\text{V}, I_D = 20\text{A}, R_G = 3\Omega$	--	16	--	$\text{ns}$
Turn-on Rise Time	$t_r$		--	9	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	36	--	
Turn-off Fall Time	$t_f$		--	11	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$	$T_C = 25^\circ\text{C}$	--	--	170	A
Body Diode Voltage	$V_{\text{SD}}$	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 20\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.2	V
Reverse Recovery Charge	$Q_{\text{rr}}$	$I_F = 20\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = 500\text{A}/\text{us}$	--	150	--	$\text{nC}$
Reverse Recovery Time	$T_{\text{rr}}$		--	30	--	ns

**Notes**

1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{\text{DD}}=50\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_G=25\Omega$

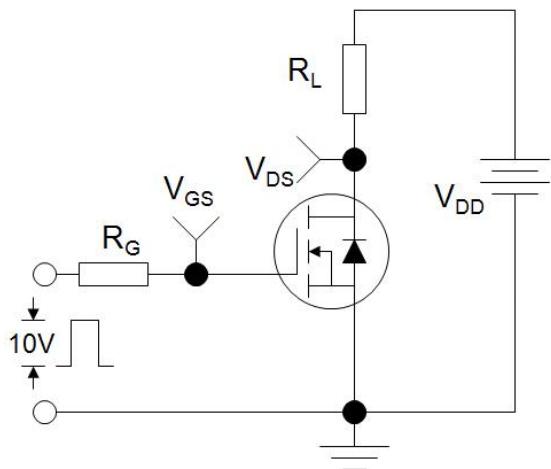
The table shows the minimum avalanche energy, which is 900mJ when the device is tested until failure

3. Identical low side and high side switch with identical  $R_G$

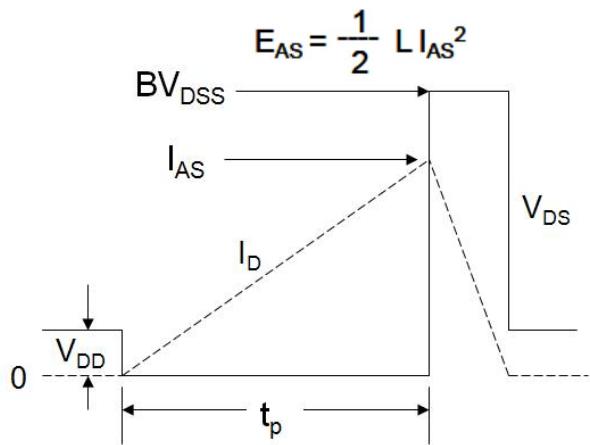
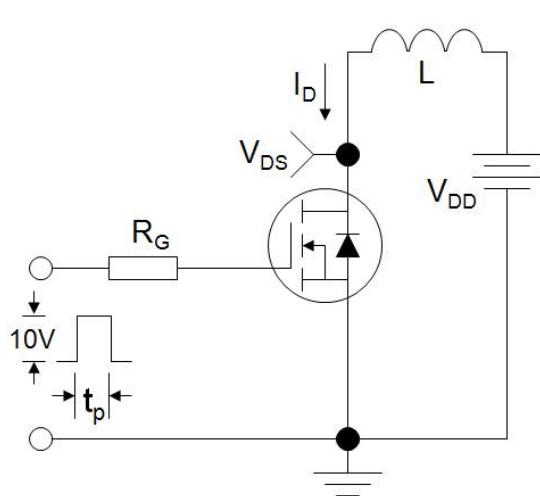
### Gate Charge Test Circuit



### Switch Time Test Circuit

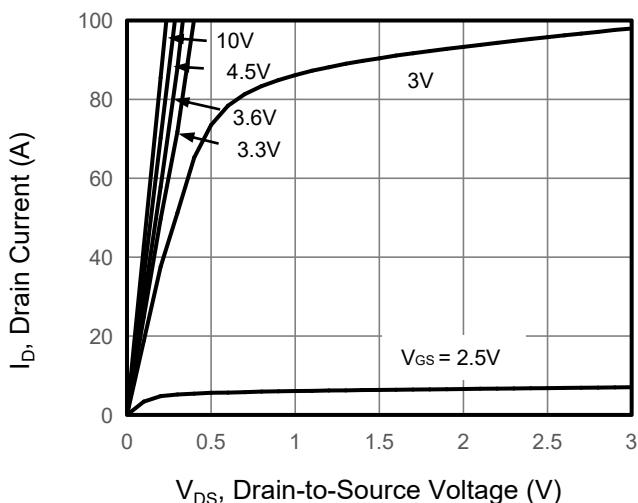


### EAS Test Circuit

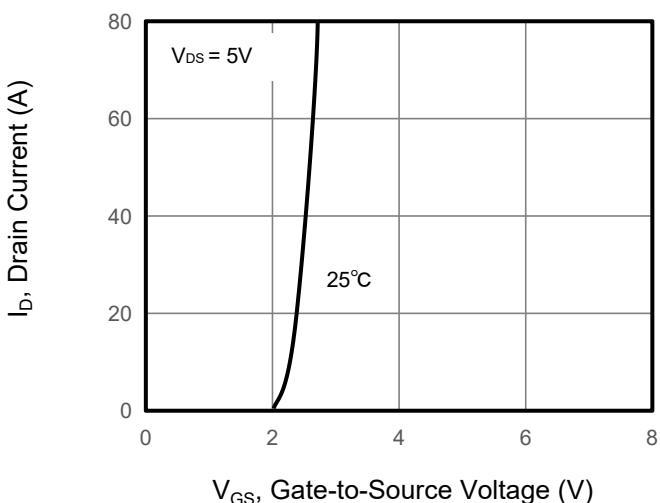


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

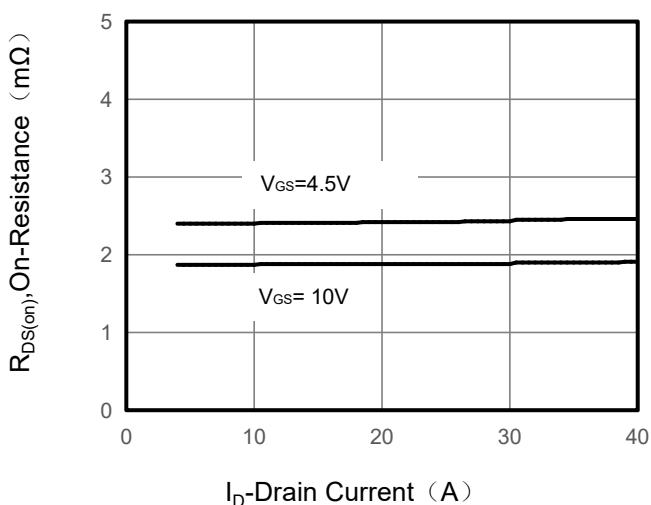
**Figure 1. Output Characteristics**



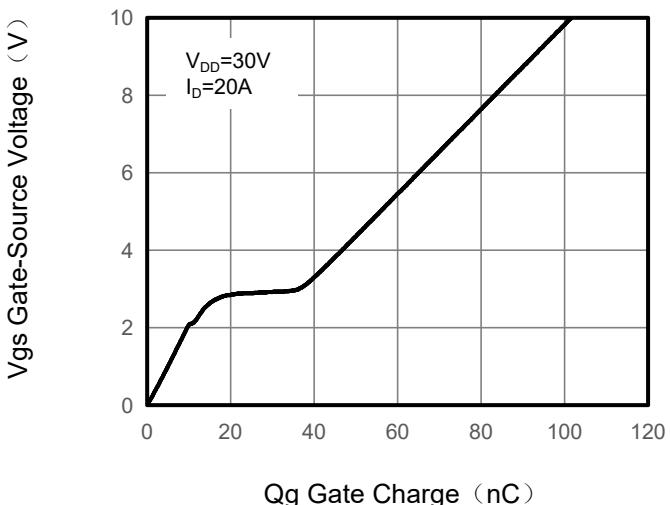
**Figure 2. Transfer Characteristics**



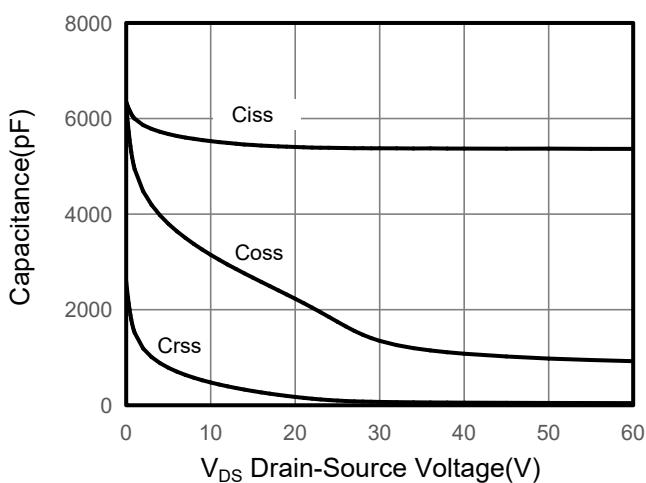
**Figure 3. Drain Source On Resistance**



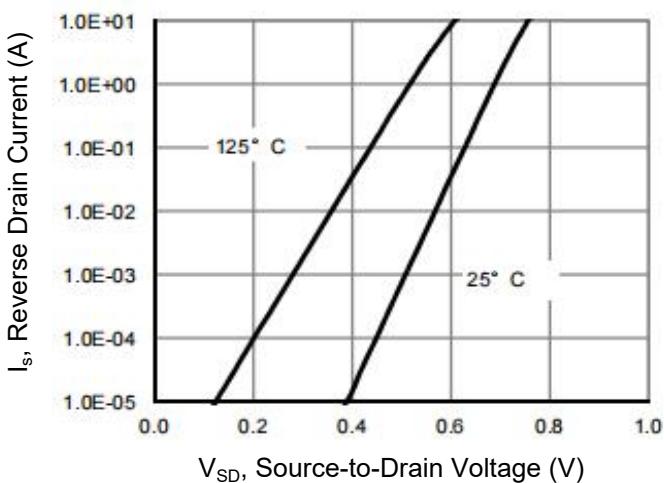
**Figure 4. Gate Charge**



**Figure 5. Capacitance vs Vds**

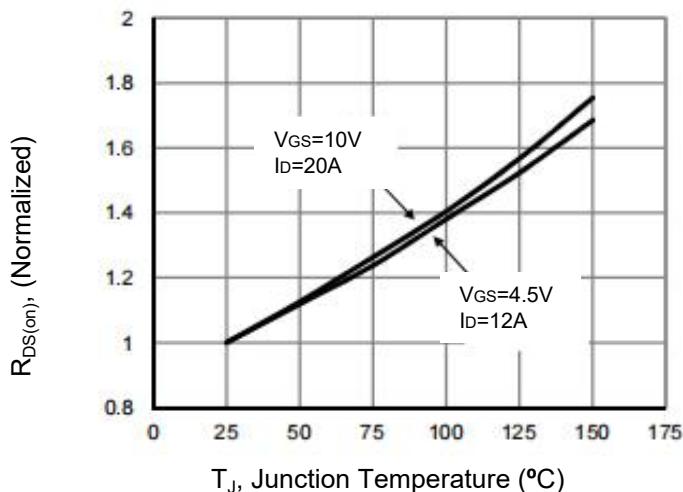


**Figure 6. Source-Drain Diode Forward**

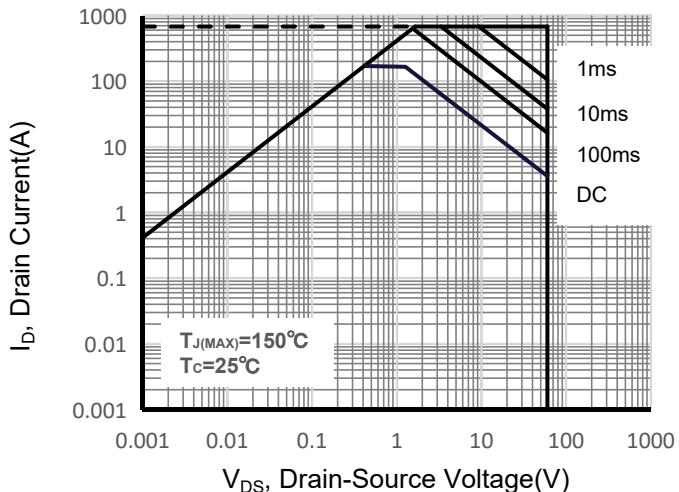


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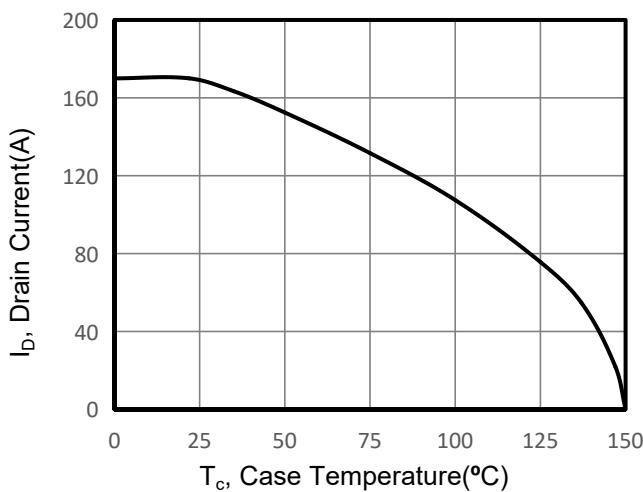
**Figure 7. Drain-Source On-Resistance**



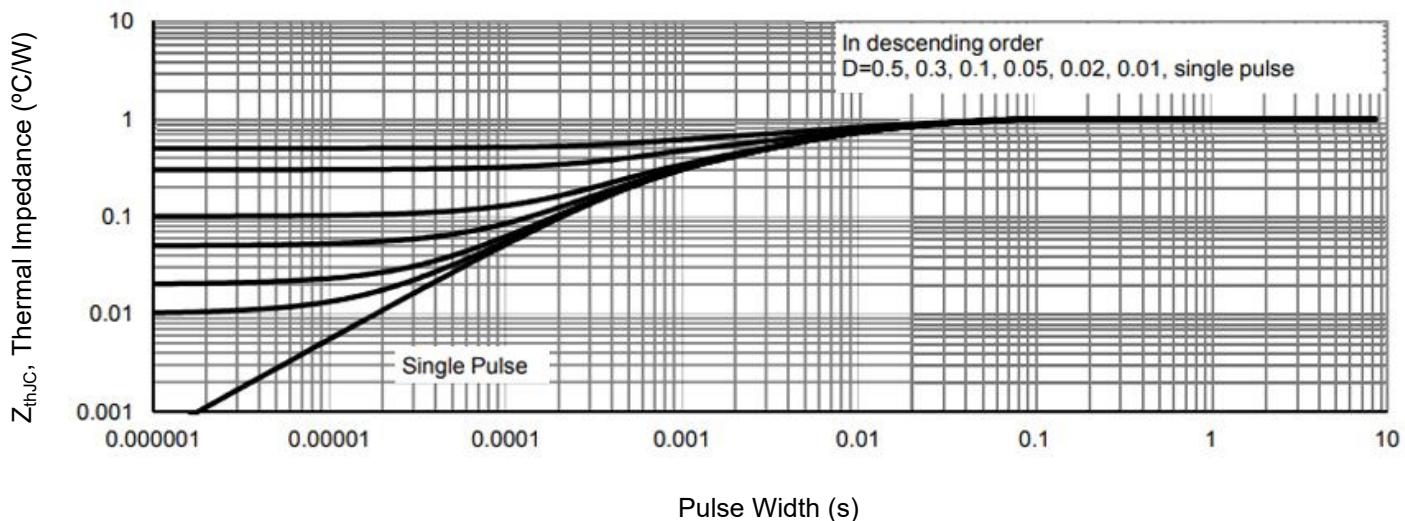
**Figure 8. Safe Operation Area**

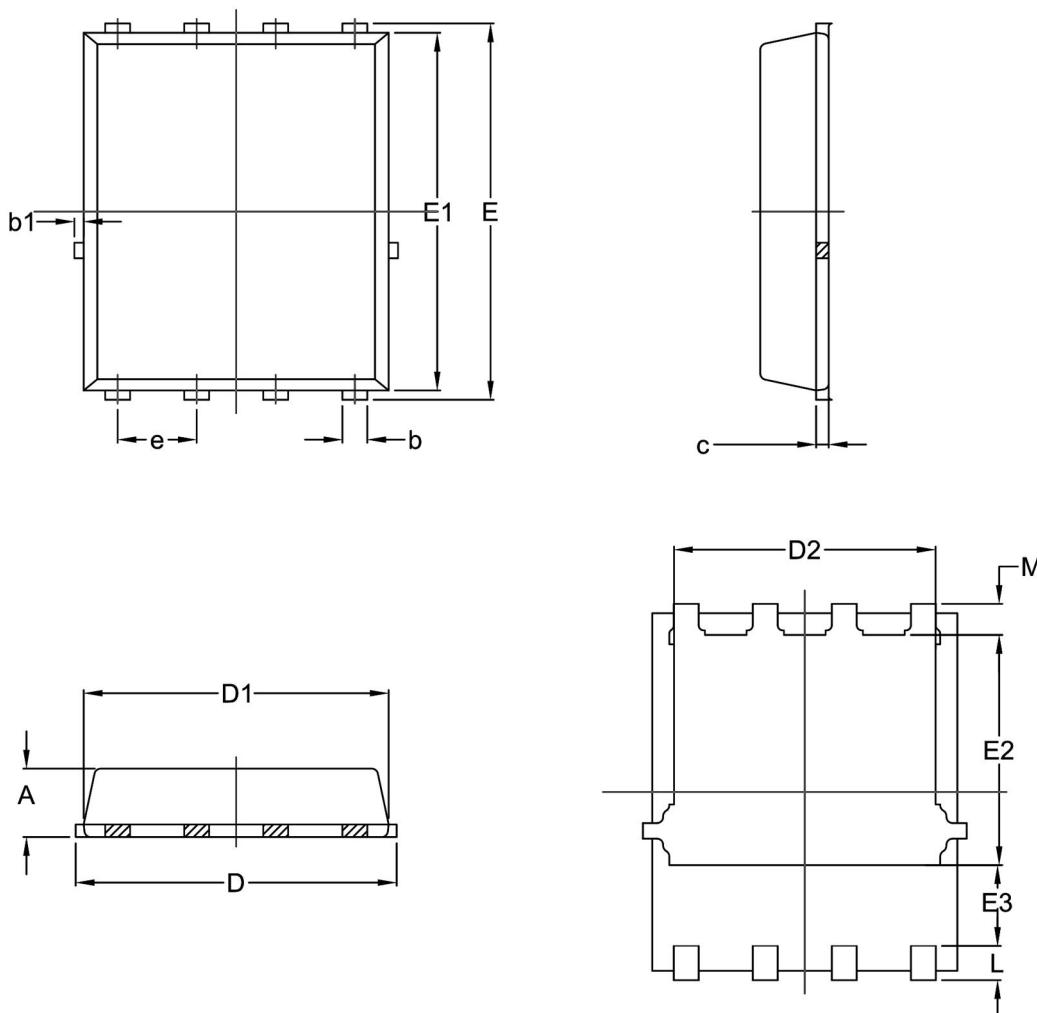


**Figure 9. Maximum Continuous Drain Current vs Case Temperature**



**Figure 10. Normalized Maximum Transient Thermal Impedance**



**DFN5\*6-8L Package Information**

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	1.00	1.10	1.20
b	0.30	0.40	0.50
b1	0.02	0.15	0.22
c	0.15	0.20	0.35
D	4.95	5.15	5.35
D1	4.80	4.90	5.00
D2	4.00	4.20	4.40
E	5.95	6.05	6.25
E1	5.65	5.75	5.85
E2	3.50	3.70	3.90
E3	1.10	/	/
e	1.27		
L	0.40	0.55	0.70
M	0.35	0.50	0.65